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FCH070N60E

#### **April 2015**

# N-Channel SuperFET® II Easy-Drive MOSFET

**600 V, 52 A, 70 m**Ω

#### **Features**

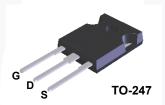
- 650 V @ T<sub>J</sub> = 150°C
- Typ.  $R_{DS(on)}$  = 58 m $\Omega$
- Ultra Low Gate Charge (Typ. Q<sub>g</sub> = 128 nC)
- Low Effective Output Capacitance (Typ. C<sub>oss(eff.)</sub> = 457 pF)
- · 100% Avalanche Tested
- · RoHS Compliant

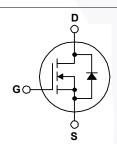
# **Applications**

- Telecom / Sever Power Supplies
- · Industrial Power Supplies

# Description

SuperFET® II MOSFET is Fairchild Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET II MOSFET easy-drive series offers slightly slower rise and fall times compared to the SuperFET II MOSFET series. Noted by the "E" part number suffix, this family helps manage EMI issues and allows for easier design implementation. For faster switching in applications where switching losses must be at an absolute minimum, please consider the SuperFET II MOSFET series.





# Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol			FCH070N60E	Unit	
V <sub>DSS</sub>	Drain to Source Voltage			600	V
	Cata ta Causaa Valtaria	- DC		±20	.,
$V_{GSS}$	Gate to Source Voltage	- AC	(f > 1 Hz)	±30	_ V
Davis Ossess		- Continuous (T <sub>C</sub> = 25°C)	/	52	Α
Drain Current	- Continuous (T <sub>C</sub> = 100°C)		33	A	
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	156	Α
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)			1128	mJ
I <sub>AR</sub>	Avalanche Current (Note 1)		9.5	Α	
E <sub>AR</sub>	Repetitive Avalanche Energy	4.8	mJ		
dv/dt	MOSFET dv/dt			100	1//20
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	20	V/ns
D	Davies Dissination	(T <sub>C</sub> = 25°C)		481	W
$P_{D}$	Power Dissipation	- Derate Above 25°C		3.85	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range			-55 to +150	°C
T <sub>L</sub>	Maximum Lead Temperature for	Soldering, 1/8" from Case for 5	Seconds	300	°C

## **Thermal Characteristics**

Symbol	Parameter	FCH070N60E	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.26	°C/W
$R_{\theta,IA}$	Thermal Resistance, Junction to Ambient, Max.	40	30/00

# **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCH070N60E	FCH070N60E	TO-247	Tube	N/A	N/A	30 units

# **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Chara	cteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 10 \text{ mA}, T_J = 25^{\circ}\text{C}$	600	-	-	V
	Dialii to Source Breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 10 \text{ mA}, T_J = 150^{\circ}\text{C}$	650	-	-	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 10 mA, Referenced to 25°C	-	0.7	-	V/°C
1	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V	-	-	1	μА
IDSS	Zero Gate voltage Drain Current	$V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	3.4	-	μΑ
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA

## **On Characteristics**

V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2.5	-	3.5	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 26 \text{ A}$	-	58	70	mΩ
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 26 A	-	44	-	S

# **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 200 V V 0 V	-	3705	4925	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 380 V, V <sub>GS</sub> = 0 V, f = 1 MHz		116	155	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			12.3	20	pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	$V_{DS} = 0 \text{ V to } 480 \text{ V}, V_{GS} = 0 \text{ V}$	- \	457	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10V	$V_{DS} = 380 \text{ V}, I_{D} = 26 \text{ A},$	- \	128	166	nC
$Q_{gs}$	Gate to Source Gate Charge	V <sub>GS</sub> = 10 V	-	18	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge	(Note 4)	-	54	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	0.6	-	Ω

# **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		- /	29	68	ns
t <sub>r</sub>		$V_{DD} = 380 \text{ V}, I_D = 26 \text{ A},$	- /	28	66	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS}$ = 10 V, $R_g$ = 4.7 $\Omega$	-/	122	254	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	-	28	66	ns

#### **Drain-Source Diode Characteristics**

Is	Maximum Continuous Drain to Source Diode Forward Current			-	52	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current			-	156	Α
$V_{SD}$	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 26 A	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 26 A,	-	463	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> /dt = 100 A/μs	-	10.4	-	μС

#### Notes:

- 1. Repetitive rating: pulse width limited by maximum junction temperature.
- 2.  $I_{AS}$  = 9.5 A,  $R_G$  = 25  $\Omega$ , Starting  $T_J$  = 25°C
- 3.  $I_{SD} \le$  26 A, di/dt  $\le$  200 A/ $\mu$ s,  $V_{DD} \le$  380 V, Starting  $T_J$  = 25°C
- 4. Essentially independent of operating temperature.

# **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

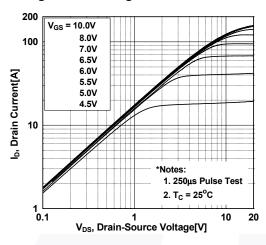


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

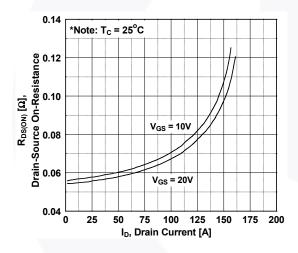


Figure 5. Capacitance Characteristics

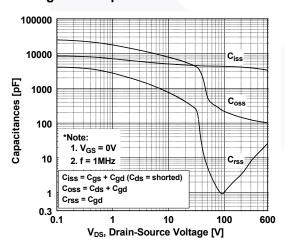


Figure 2. Transfer Characteristics

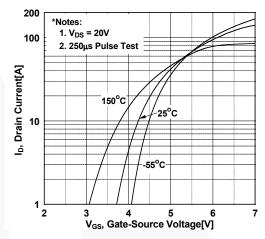


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

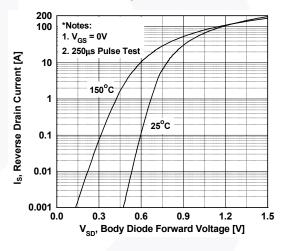
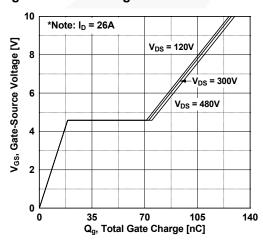


Figure 6. Gate Charge Characteristics



# **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

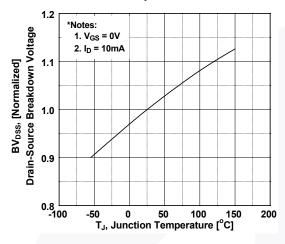


Figure 9. Maximum Safe Operating Area

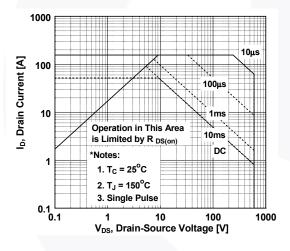


Figure 11. Eoss vs. Drain to Source Voltage

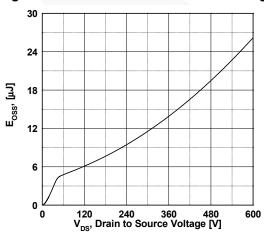


Figure 8. On-Resistance Variation vs. Temperature

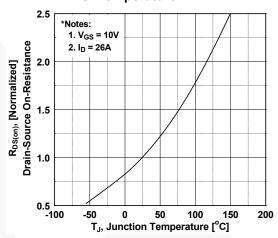
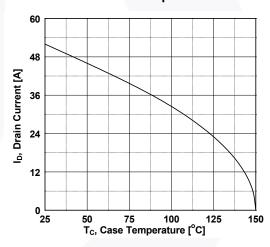
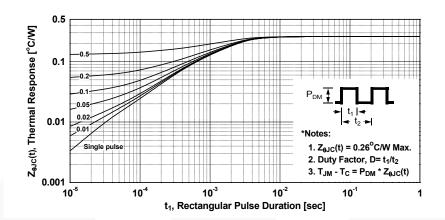


Figure 10. Maximum Drain Current vs. Case Temperature



# **Typical Performance Characteristics** (Continued)

Figure 12. Transient Thermal Response Curve



# Figure 13. Gate Charge Test Circuit & Waveform

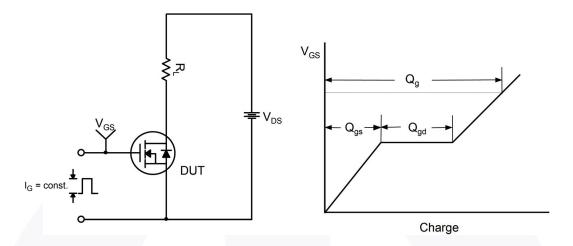


Figure 14. Resistive Switching Test Circuit & Waveforms

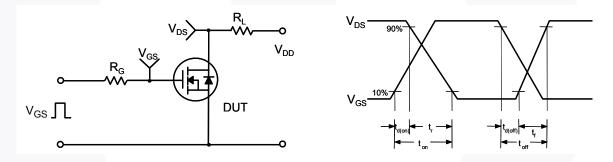
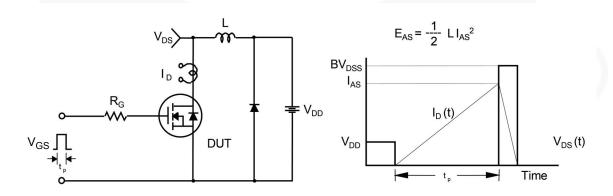


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms



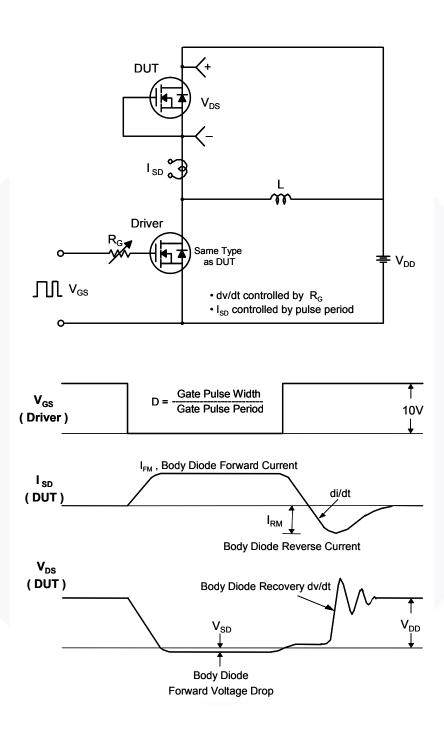
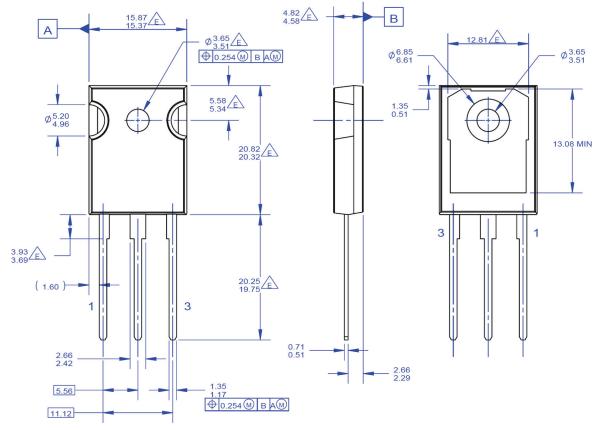


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

## **Mechanical Dimensions**



- NOTES: UNLESS OTHERWISE SPECIFIED
- A. PACKAGE REFERENCE: JEDEC TO-247,
- ISSUE E, VARIATION AB, DATED JUNE, 2004. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- ALL DIMENSIONS ARE IN MILLIMETERS.
  DRAWING CONFORMS TO ASME Y14.5 1994
- DOES NOT COMPLY JEDEC STANDARD VALUE
  F. DRAWING FILENAME: MKT-TO247G03\_REV01

## Figure 16. TO-247, Molded, 3-Lead, Jedec AB Long Leads

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